

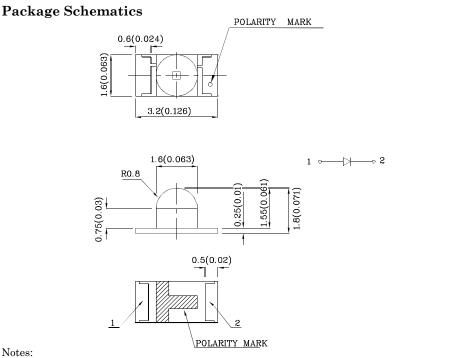
Part Number: ZMOK55W-3

3.2x1.6mm SMD CHIP LED LAMP

Features

- \bullet Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		MOK (AlGaInP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	195	mA	
Power Dissipation	PD	75	mW	
Operating Temperature	$T_{\rm A}$	$\text{-}40 \sim \text{+}85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$	-0	

Operating Characteristics (T _A =25°C)		MOK (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2.1	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V	
Reverse Current (Max.) (V _R =5V)	I_R	10	uA	
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	610*	nm	
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	601*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	29	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	$_{\rm pF}$	

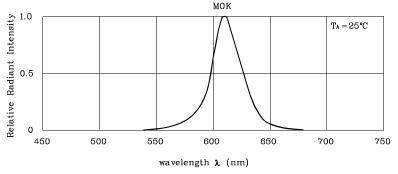
Part Number	Emitting Color	Emitting Material	- Long-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* λΡ nm	Viewing Angle 20 1/2
				min.	typ.		
ZMOK55W-3	Orange	AlGaInP	Water Clear	700 500*	$1590 \\ 995*$	610*	35°

 ${\rm *Luminous\ intensity\ value\ and\ wavelength\ are\ in\ accordance\ with\ CIE127-2007\ standards.}$

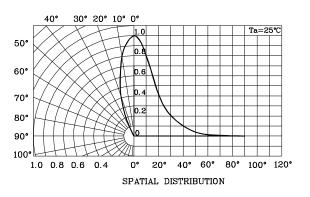
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SDSA0098 V9-X Layout: Maggie L.

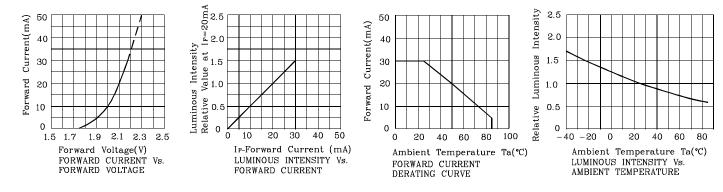




RELATIVE INTENSITY Vs. CIE WAVELENGTH



♦ MOK



LED is recommended for reflow soldering and soldering profile is shown below.

300 (°C) 10 s max 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 60~120s 100 50 0 150 0 50 100 200 250 300 (sec) Time Notes:

Reflow Soldering Profile for SMD Products (Pb-Free Components)

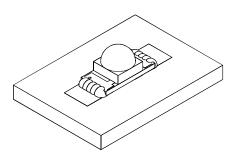
1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C Do not put stress to the epoxy resin during

З. high temperatures conditions



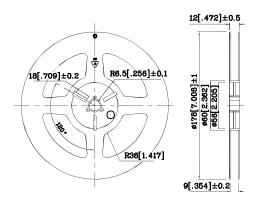
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



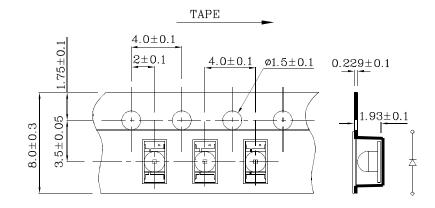
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

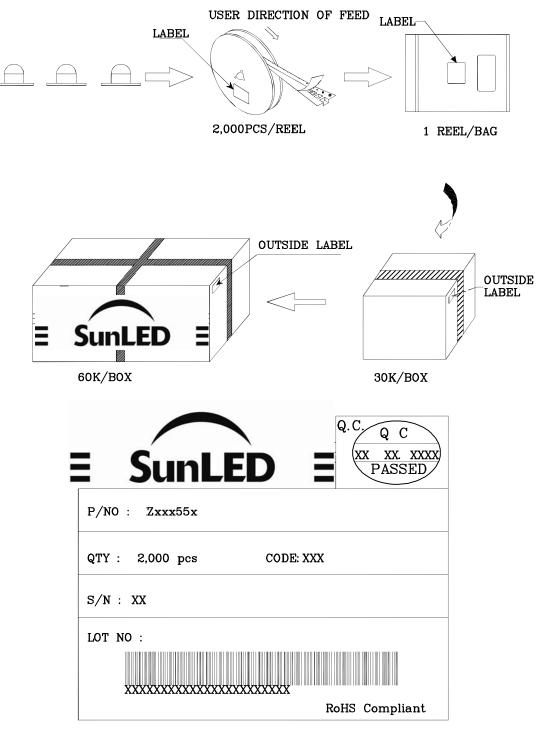
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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PACKING & LABEL SPECIFICATIONS



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